

PICTURE BOOK

Laser Decap at EAG

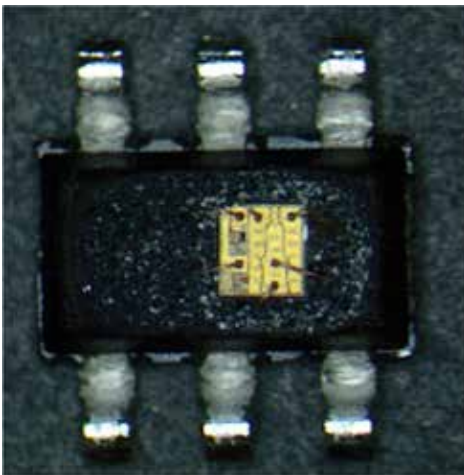
Devices As received



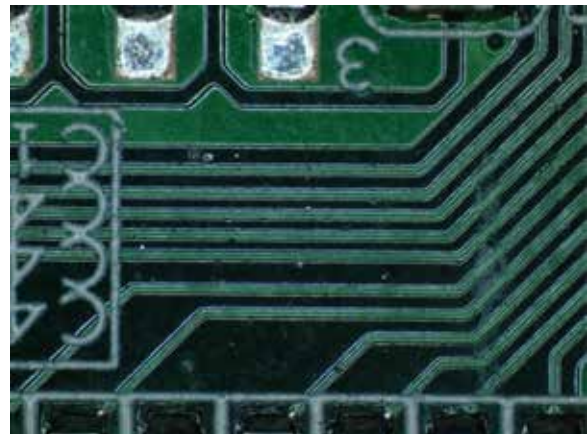
The System



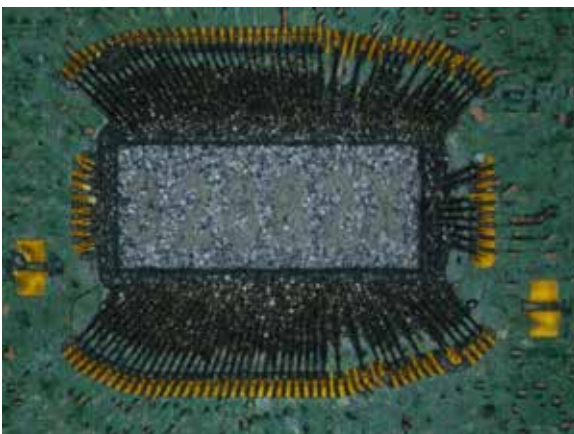
Decapped with aid of laser



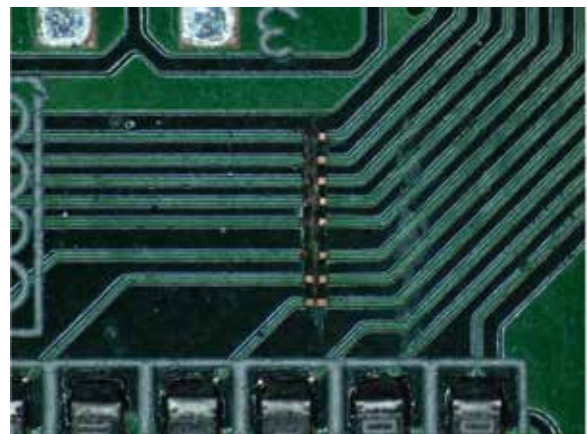
PC board top view



Stitch bonds exposed by laser

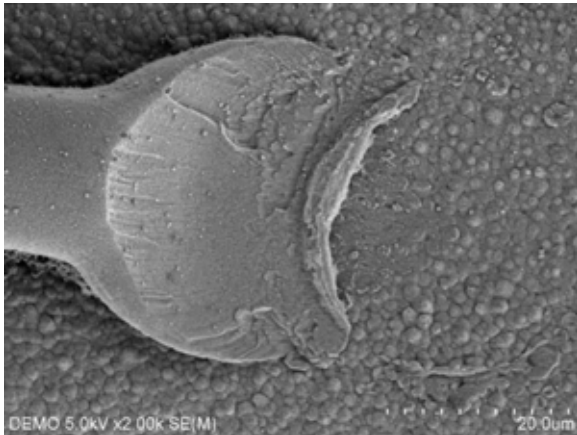


PCB after laser exposed traces for probing and cutting

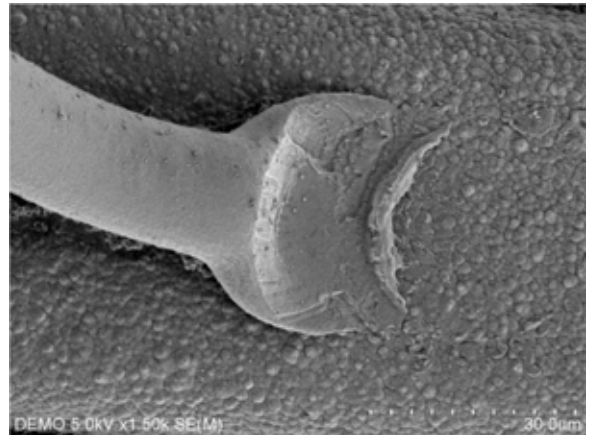


Laser Decap at EAG

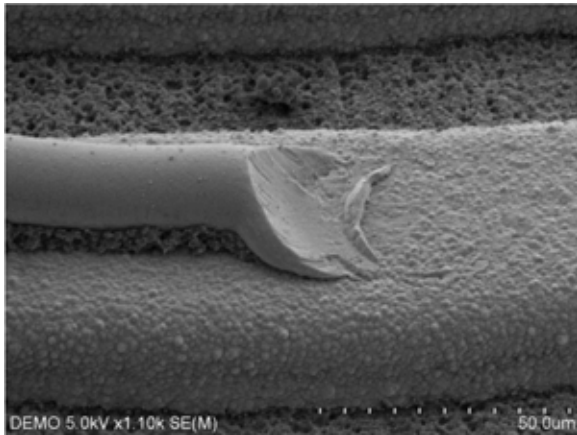
Good stitch bond top down



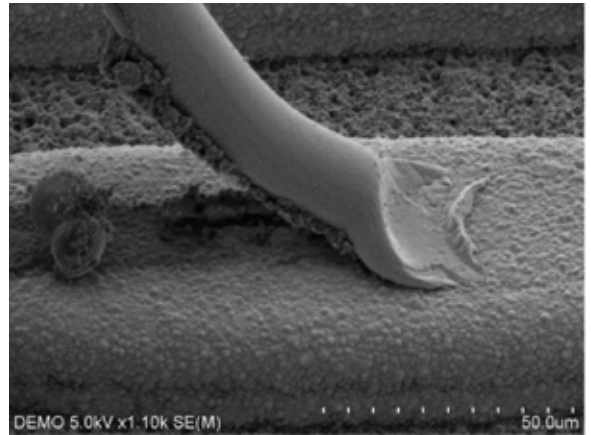
Slightly lifted stitch bond top down



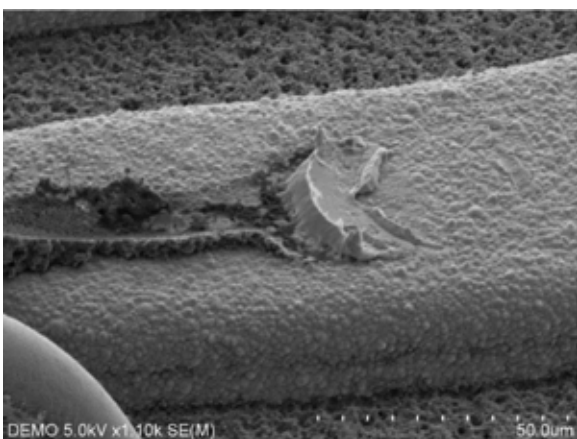
Good stitch bond 45 degree tilt



Slightly lifted stitch bond 45 degree tilt



Broken stitch bond 45 degree tilt



Broken stitch bond top down

